

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ07N10
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of	% of weight
Wafer	Silicon	7440-21-3	100.00%	0.2902%
Lead Frame	Cu	7440-50-8	97.03%	34.0224%
	Fe	7439-89-6	2.21%	
	Pb	7439-92-1	0.01%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.02%	
	Ag	7440-22-4	0.66%	
Epoxy	Ag>= 99,9 %, 粉末状 (>100nm<1mm)	7440-22-4	85.87%	0.9779%
	二乙二醇丁醚醋酸酯	124-17-4	5.40%	
	从 C36-烯化二胺和顺丁烯二酸酐得到的环状酰亚胺类	682800-79-9	3.00%	
	丙烯酸酯单体	Trade Secret	1.60%	
	丙烯酸[2-(1,2-环己基二羧基氨基)乙基]酯	106646-48-4	1.30%	
	(甲基)丙烯酸双环戊烯基氧化乙酯	68586-19-6	1.90%	
	环氧环己烷乙基三甲氧基硅烷	543576	0.45%	
	过氧化二异丙苯	2425-79-8	0.29%	
	钨(2+) 盐	80-43-3	0.19%	
Wire	copper	1947330-20-2	99.99%	1.1368%
	others	/	0.01%	
Mold Compound	Epoxy resin A	Trade Secret	5.91%	61.8933%
	Epoxy resin B	29690-82-2	3.87%	
	Phenol Resin	Trade Secret	2.20%	
	Silica(Amorphous) A	60676-86-0	80.51%	
	Silica(Amorphous) B	7631-86-9	6.88%	
	Carbon black	1333-86-4	0.63%	
Plating	Tin	7440-31-5	100.00%	1.6794%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.